

FIG. 1

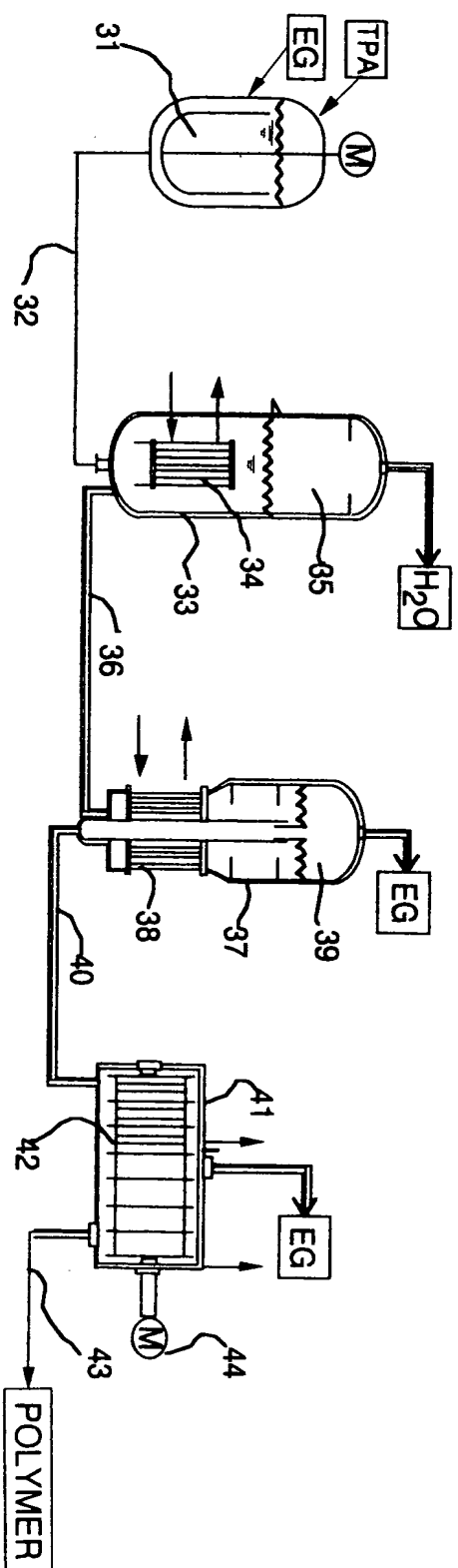


FIG. 2

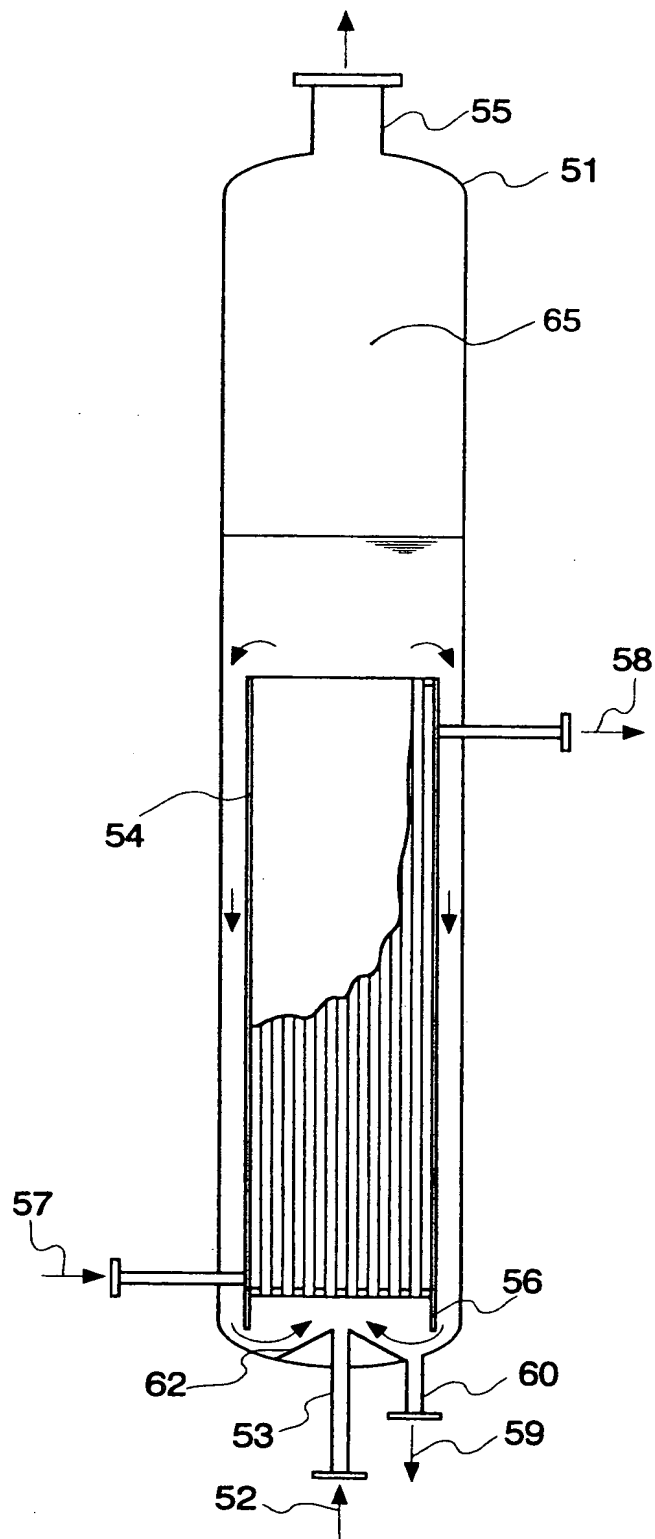
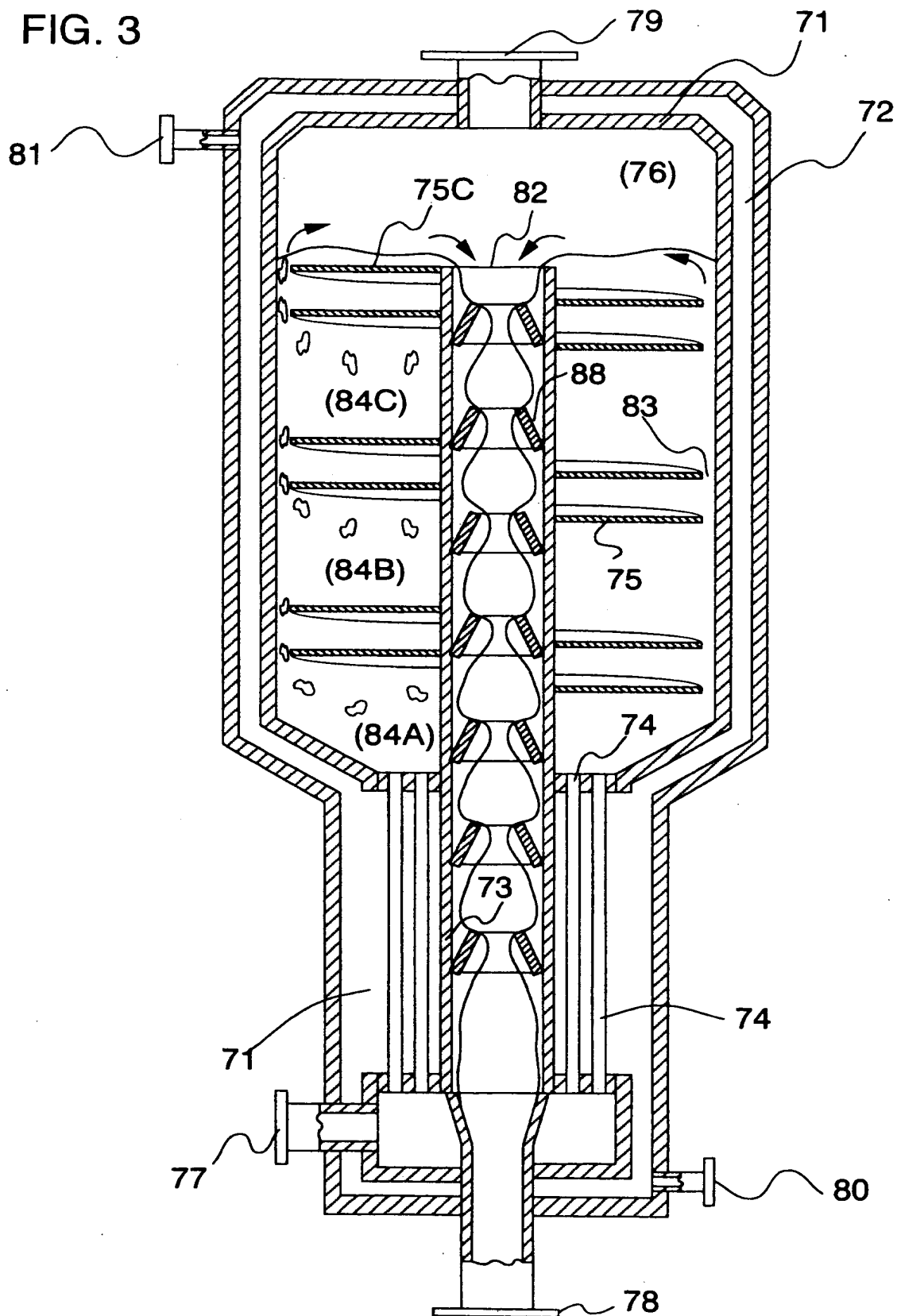


FIG. 3



This technical drawing illustrates a complex layered structure, possibly a microelectronic assembly. It features several distinct regions and components:

- Top Surface Layer (2a)**: The uppermost thin layer.
- Core Region (1)**: The central area containing internal patterns (7a, 7b).
- Intermediate Layers (6a, 6b, 8, 9, 10, 11, 12)**: A series of stacked horizontal layers.
- Vertical Interconnects (3a, 3b)**: Structures connecting different layers vertically.
- Bottom Surface Layer (2b)**: The lowermost thin layer.
- Peripheral Features (4, 5a, 5b, 13a, 13b, 14)**: Various structural elements around the perimeter and between layers.

The diagram includes five sectional planes indicated by arrows at the bottom: A-A, B-B, C-C, D-D, and E-E.

FIG. 5

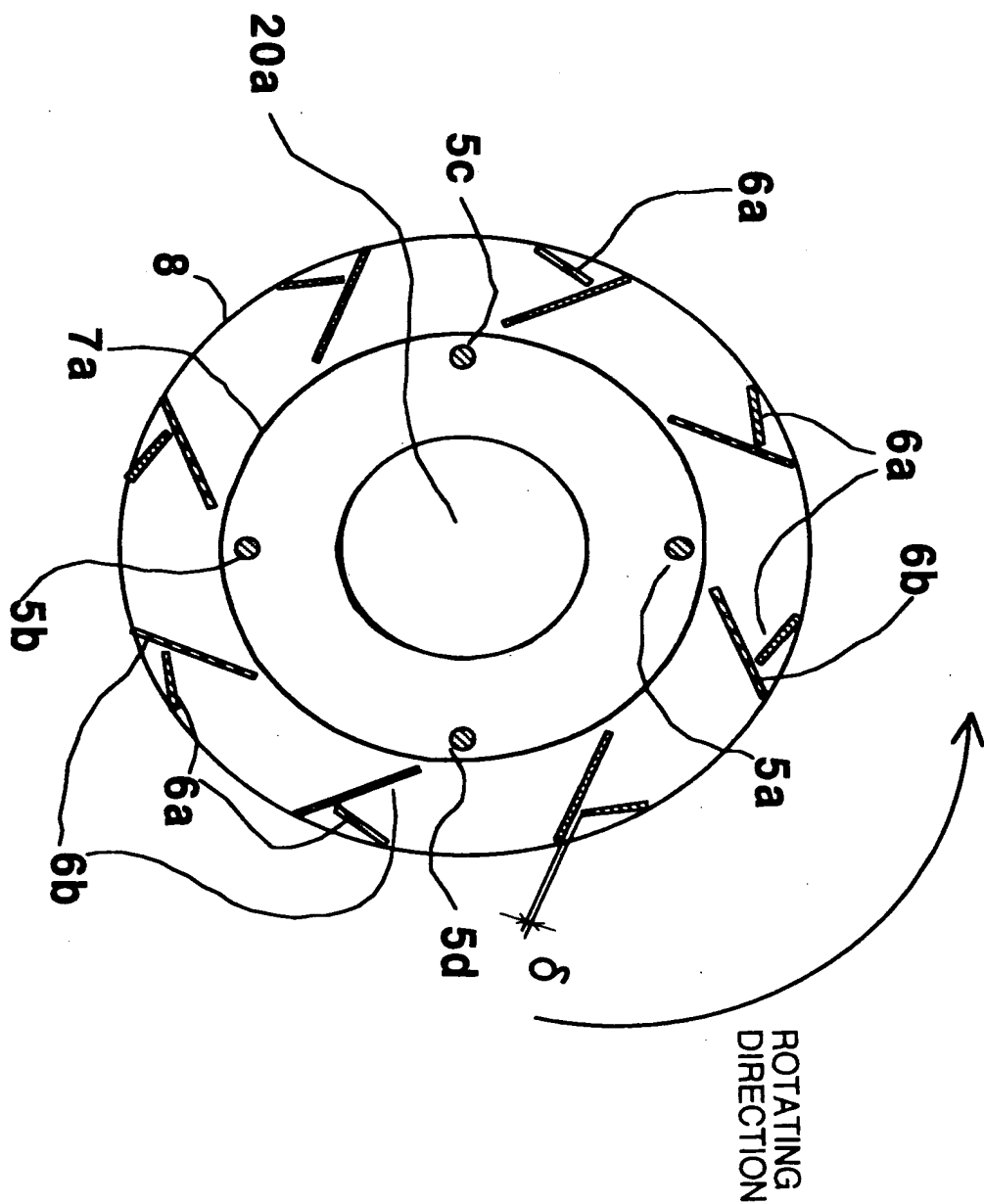


FIG. 6

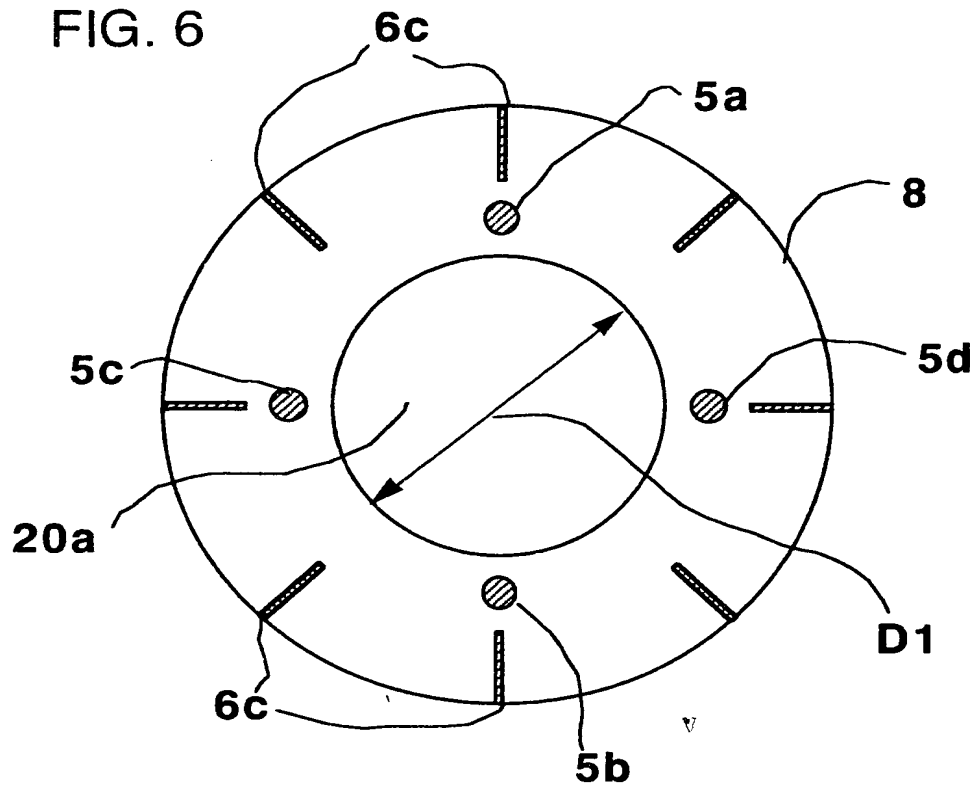
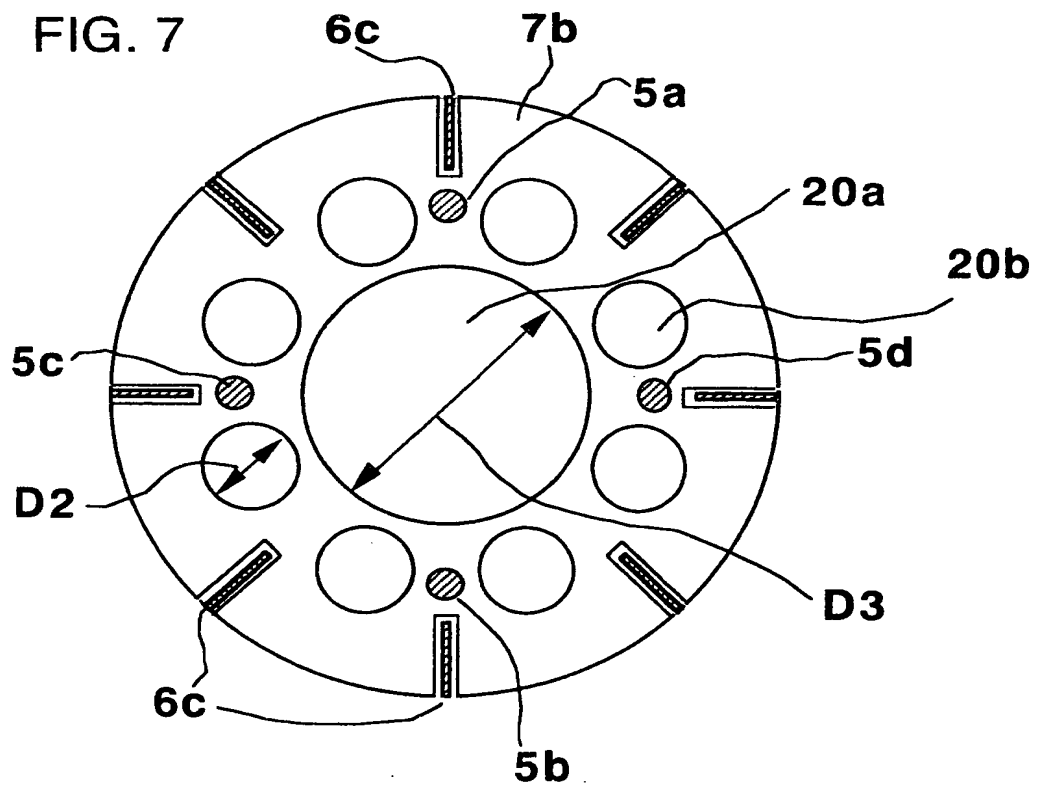


FIG. 7



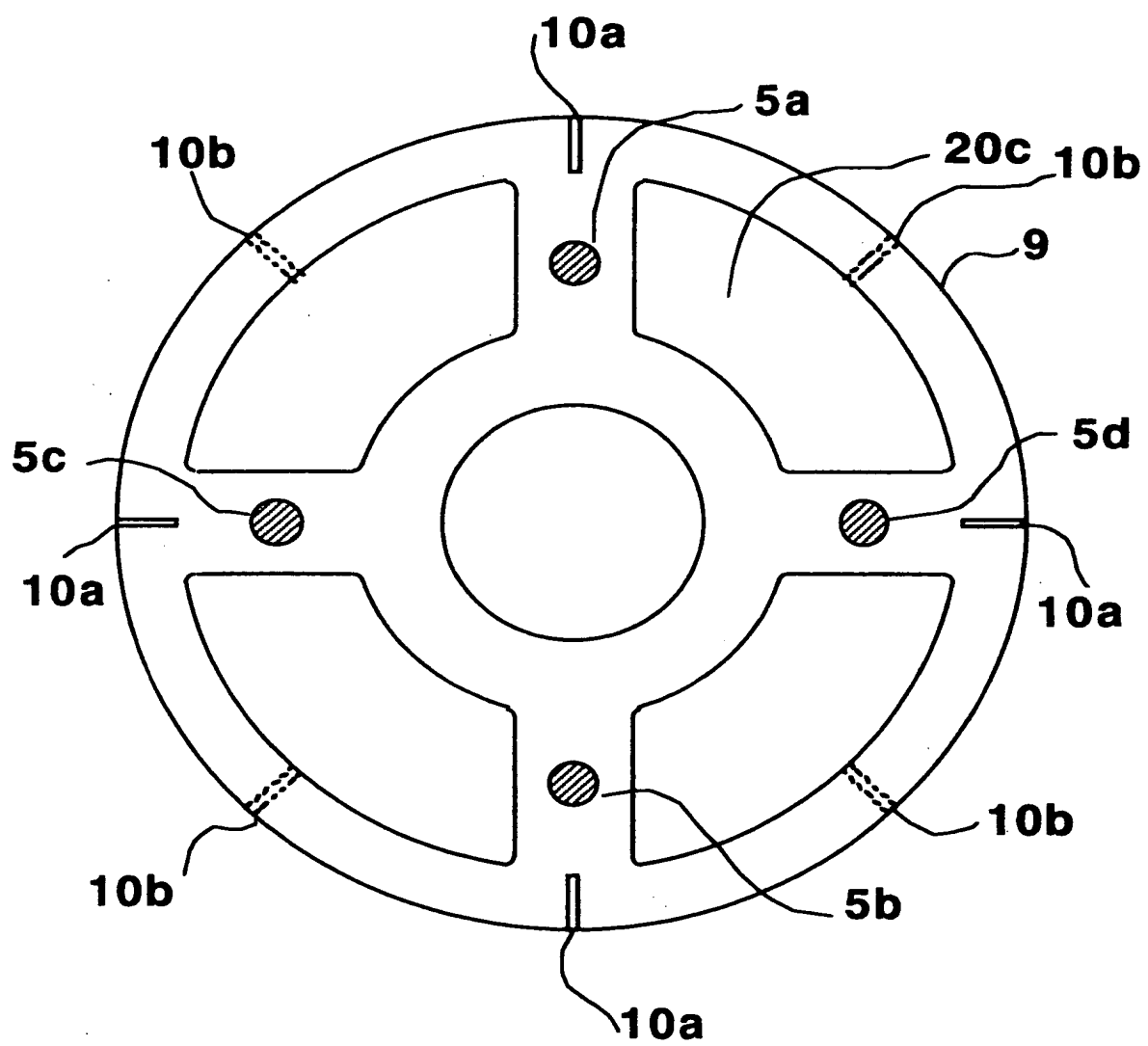
[illegible]

FIG. 9

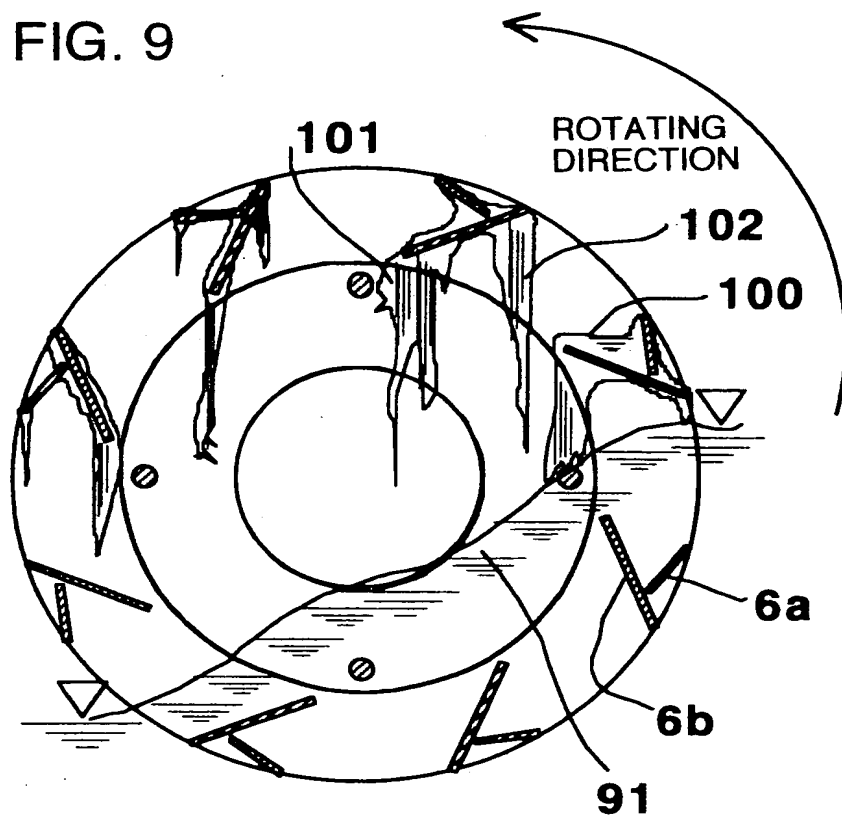


FIG. 10

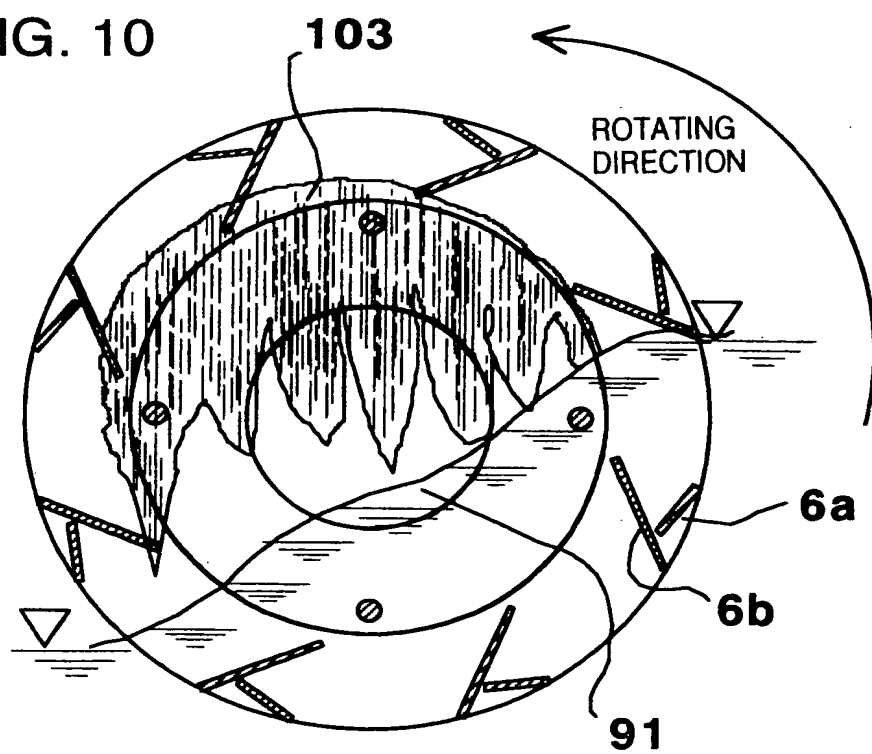


FIG. 11

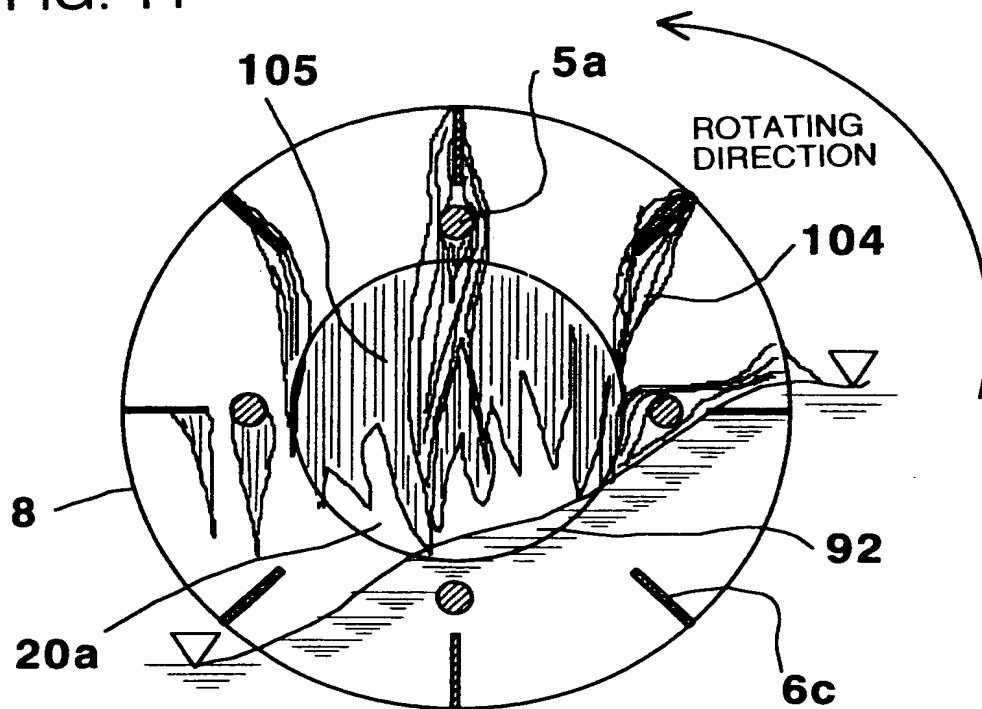
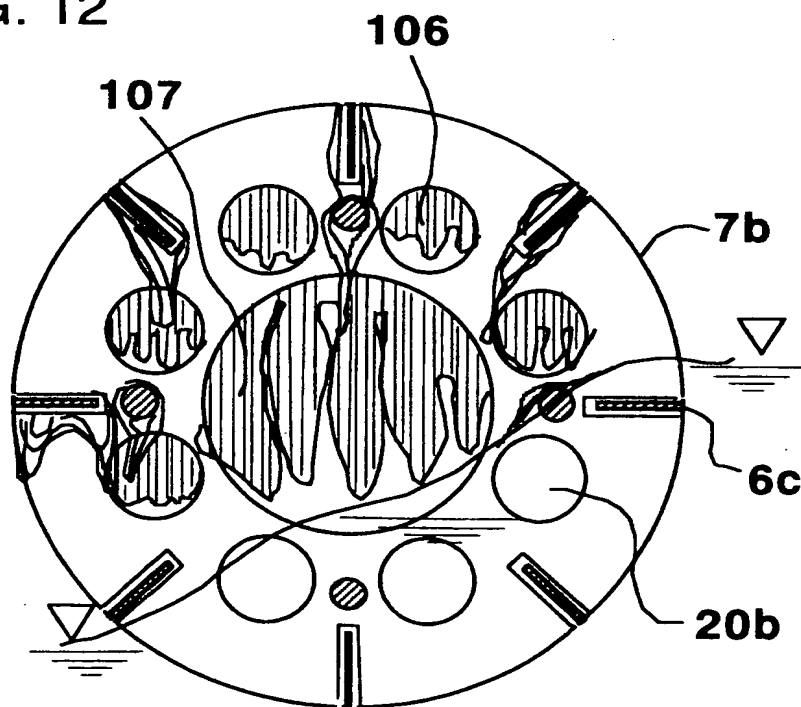
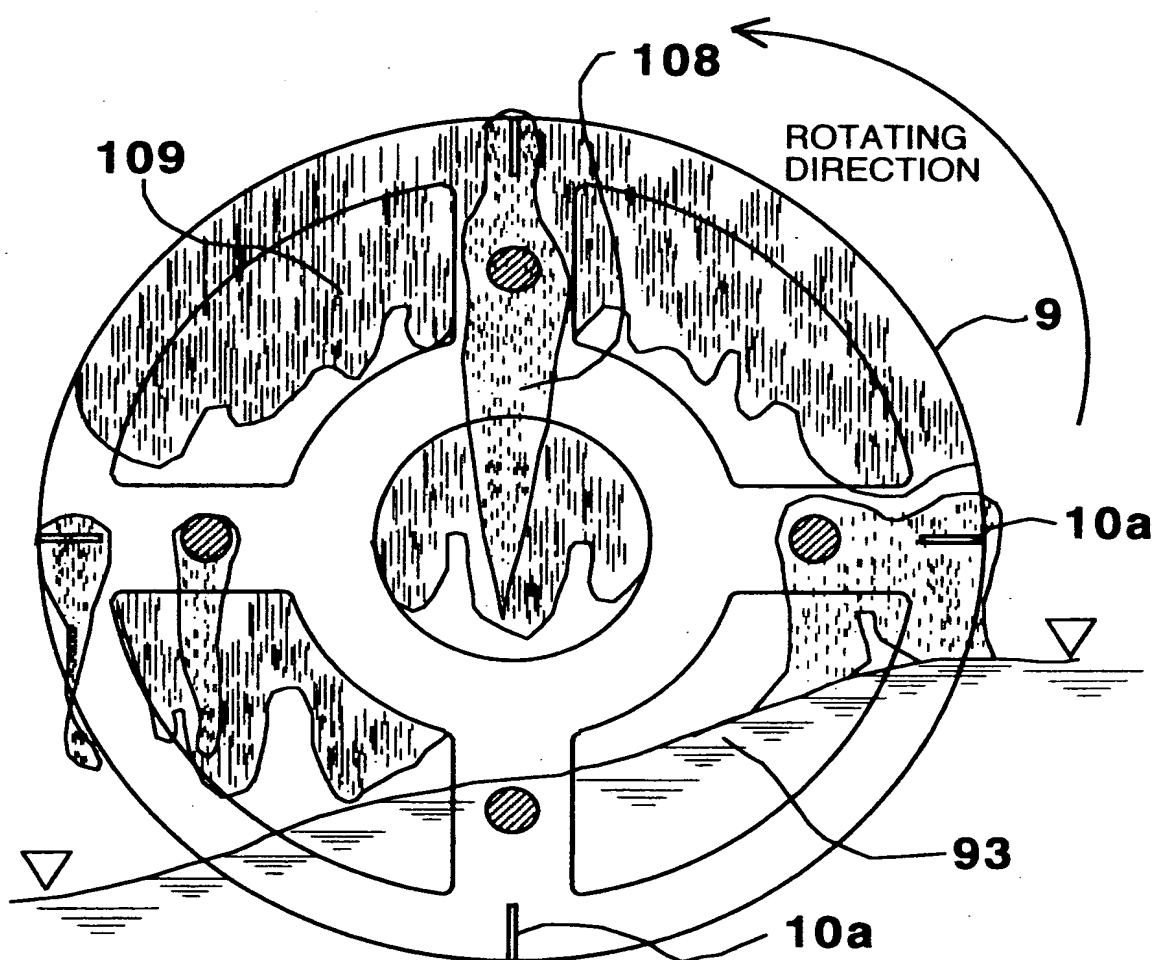


FIG. 12





[illegible]